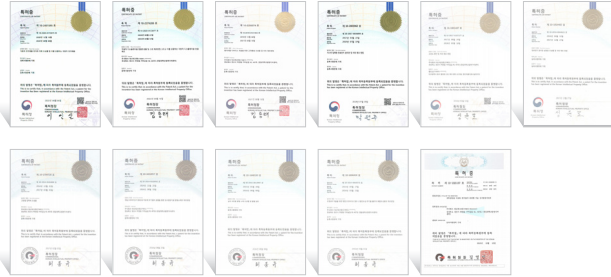




# COMPETITIVITY

## PATENTS

✓ 11 Registered ✓ 7 Applied ✓ 2 Trademark Registered



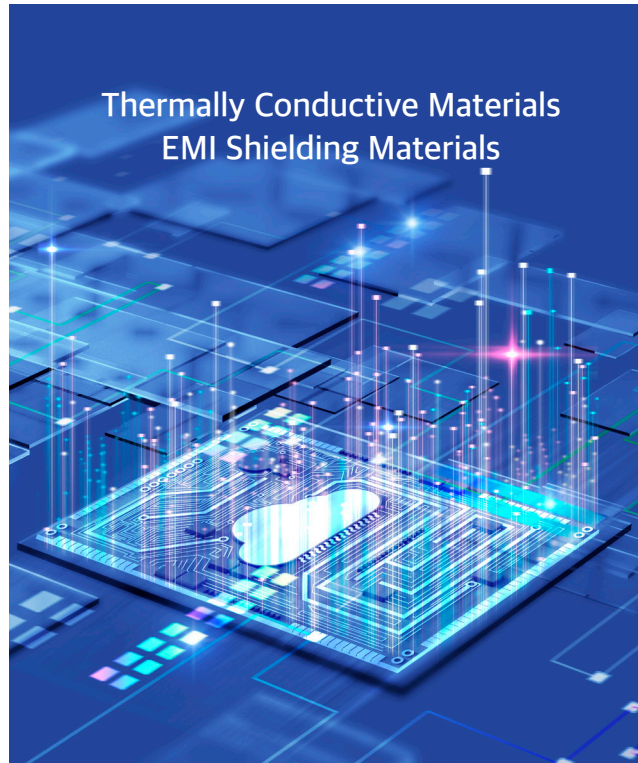
## CERTIFICATION

✓ ISO 9001 ✓ ISO 14001 ✓ Green Technology Certificate  
✓ KSM Registered(KRX) ✓ R&D Center Official Certificate



## AWARDS

✓ 2022 Gyeonsan-City Award  
✓ 2020 Best Growth Award (Ministry of SMEs and Startups)  
✓ 2020 Nuclear Industry Exhibition Award (Ministry of Trade Industry and Energy)  
✓ 2020 Local Ministry of SMEs Award  
✓ 2019 Gyeongbuk Technopark Award  
✓ 2018 Gyeongbuk Province Award



Thermally Conductive Materials  
EMI Shielding Materials



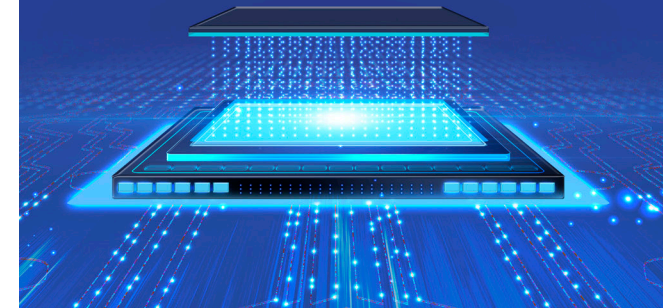
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# THERMAL SOLUTIONS for

- ✓ Electronic devices
- ✓ Semiconductors
- ✓ ECU of Automotive
- ✓ LED Chips
- ✓ Wearable devices



Thermally Conductive Materials  
EMI Shielding Materials





## Thermal Interface Materials

*Types : Emulsion, Paste, Pad, Sheet*

Wide range of electronic devices are come to the present. And the functional enhancement is consistently going on. However, they need more power and cause to increase heat much more. If heat can not escape efficiently, the performance of the device suffers. That's why thermal interface materials are becoming such an important technology in the electronics industry. Silicone-based thermal interface materials are compound materials which contain a high ratio of thermally conductive fillers. They exhibit outstanding thermal conductivity because they fit snugly in the gap between the heat-generating unit and the heatsink.

Thermal interface materials have been generally used in all heat dissipation modules to fill the gaps and uneven holes on the surface of the electronic materials, otherwise it will seriously hinder heat conduction. With the pursuit of high-power performance in electronic products, in addition to the pursuit of thermal conductivity of thermal interface materials, material reliability and the reduction of interface thermal resistance are more important issues. The types of thermal interface materials include thermal pad, thermal tape, thermal grease, and thermal putty. In order to accelerate heat transfer by filling the gap between the chip heat source and the heat sink, the heat energy of the chip is effectively transferred to the heat sink fins, which also improves the life of the chip and the product usage efficiency.



## APPLICATIONS

- ✓ Electronic devices
- ✓ Semiconductors
- ✓ ECU of Automotive
- ✓ LED Chips
- ✓ Wearable devices

Thermal Pad is a solid product in thermal interface material TIM (Thermal Interface Material). It is usually applied in sheet-like construction. Its main function is to fill the micro-voids and surface unevenness generated when two materials are joined or contacted. holes, reducing the resistance to heat transfer. The thermal conductive silicone sheet is also known as the thermal pad, thermally conductive pad, soft thermally conductive pad, etc. Generally speaking, the thermal conductive silicone sheet is composed of silicone rubber combined with thermal powder to achieve Thermal Pad thermal conductivity, insulation, compressibility, etc. different characteristics.

Comprehensive consideration, the gap distance, tolerance, mechanism assembly, etc. between the heating element and the heat sink, as long as the Thermal Pad can effectively contact the surfaces of the two objects, the smaller the thickness, the larger the thermal conductivity, and the larger the contact area, all are It is the key to effectively improve heat transfer. At present, it has been widely used in 5G communication, server, battery industry, artificial intelligence, electric vehicle industry, military, industrial computer, medical, 3C computer, green energy, and other industries.

Thermal conductive double-sided tape with high thermal conductivity, high viscosity, high electrical insulation, and wide temperature tolerancelt can be easily applied to heat sinks, heat dissipation modules, CPU microprocessor heat dissipation, and LED lamps and lanterns. It can be directly attached instead of locking screws or push pins, and the heat conduction effect is good. It can fill the gap between the heat source and metal products. The gap is uneven, and the heat generated by electronic products is taken away to achieve the effect of cooling and heat dissipation.



## EMI SHIELDING MAERIALS

Specializes in the design and manufacture of standard and customized board level shielding products. Our comprehensive selection of one-piece, two-piece and multi-zone shields are available in both surface mount and through-hole configurations. With our unlimited design flexibility, material options, and utilization of our standard product features, our engineers work closely with our customers to create a specific board level shield solution to solve even the most complex applications in the most cost effective manner possible. Offers optimum specifications for electronic devices pursuing thinness and lightness, including excellent bending and sliding properties. Conductive Elastomers are designed for applications which require both EMI shielding and environmental sealing.

The compound formulations are developed by combining elastomeric polymers with highly conductive fillers, providing excellent EMI shielding and sealing across a wide temperature range. All formulations are compounded to be compatible with common fluids and to resist compression set resulting in years of continuous service. Our Conductive Elastomers are available in standard and custom configurations including Extruded Profiles, Sheet Stock, Custom Molded, and Die-Cut gaskets.

